

Series 351000 SSOP-to-DIP RoHS/WEEE-Compliant Adapter

FEATURES

- RoHS/WEEE-Compliant
- Allows the use of 0.65mm pitch surface mount ICs in thru-hole designs.
- Ideal for prototyping and testing/evaluating SSOP ICs.
- Adapter can be cut to smaller sizes by end user.
- Consult factory for Panelized Form or for mounting of consigned ICs.

GENERAL SPECIFICATIONS

- ADAPTER BODY: 0.062 [1.58] thick FR-4 or IS410 per IPC 4101C/26 with 1-oz. Cu traces, both sides
- PADS: finished with ENIG (Immersion Au over Electroless Ni)
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: 10µ [0.25µ] min. Au per MIL-G-45204 over 100µ [2.54µ] min. Ni per SAE AMS-QQ-N-290
- CURRENT RATING: 1 amp
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

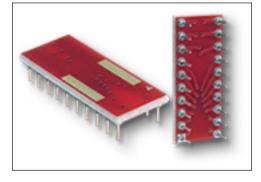
- SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia.
- · Will plug into standard IC socket

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED

"A" # OF PINS PER ROW x 0.100 [2.54] "B" (# OF PINS PER ROW -1) x 0.100 [2.54] "C" (# OF PADS PER ROW -1) x 0.0256 [0.65]

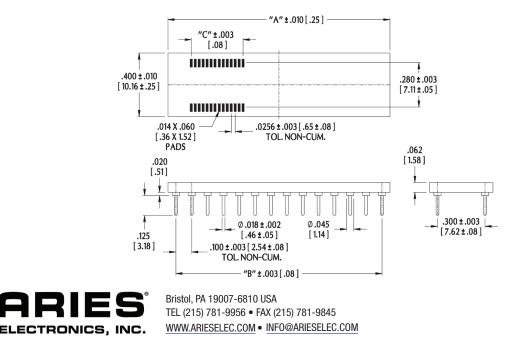
CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

16-351000-11RC 16-351000-11RC-P for Panelized Version





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